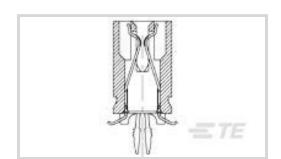
TE Internal #: 5145113-1

Board-to-Board, 184 Position, 1.27 mm [.05 in] Centerline, Vertical, Natural, 15.49 mm [.61 in] Height, PCI & PCI Express Connectors

View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 184

Centerline (Pitch): 1.27 mm [.05 in]

Contact Mating Area Plating Material Thickness: [30 µin]

PCB Mount Orientation: Vertical

Contact Current Rating (Max)

Contact Underplating Material

Contact Base Material

Contact Mating Area Plating Material

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Configuration Features	
Number of PCB Mount Retention Features	2
Number of Positions	184
PCB Mount Orientation	Vertical
Ejector	Without
Electrical Characteristics	
Operating Voltage	203 VAC
Body Features	
PCB Retention Feature Material	Brass
PCB Retention Feature Plating Material	Tin
Product Weight	15.903 g
Primary Product Color	Natural
Contact Features	

1.1 A

Nickel

Gold (Au)

Phosphor Bronze



PCB Contact Termination Area Plating Material	Tin
	30 μin
Termination Features	
Termination Method to PCB	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
PCB Mount Retention Type	Hold-Down Post
Housing Features	
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	1.27 mm[.05 in]
Dimensions	
PCB Thickness (Accepted)	.62 mm[.024 in]
Connector Length	5.04 mm[.198 in]
Connector Height	15.49 mm[.61 in]
Connector Width	.35 mm[.014 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Bus Type	PCI
Packaging Features	
Packaging Method	Box & Carton
Packaging Quantity	32

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Yet Reviewed
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Not reviewed for China RoHS compliance
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247)



Candidate List Declared Against: JUNE 2024 (241)

Does not contain REACH SVHC

Halogen Content

Not Low Halogen - contains Br or Cl > 900 ppm.

Solder Process Capability Reflow solder capable to 245°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts







Customers Also Bought









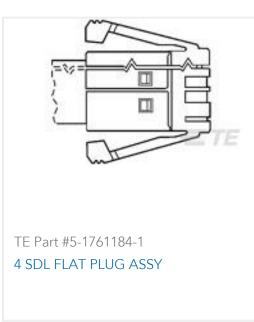














Documents

Product Drawings

CONNECTOR ASSEMBLY, DUAL POSIT

English

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_5145113-1_O.2d_dxf.zip

English

Customer View Model

ENG_CVM_5145113-1_O.3d_igs.zip

English

Customer View Model

ENG_CVM_5145113-1_O.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English